

Receipt date: 04/21/2009

Doc code: IDS

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10542040 - GAU: 1795

PTO/SB/08a (03-09)

Approved for use through 04/30/2009. OMB 0651-0031

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<b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b> ( Not for submission under 37 CFR 1.99)	Application Number	10542040
	Filing Date	2006-02-06
	First Named Inventor	John Mize
	Art Unit	1795
	Examiner Name	Jason Berman
	Attorney Docket Number	H0004870.70759 US -4015

U.S.PATENTS						
Examiner Initial*	Cite No	Patent Number	Kind Code <sup>1</sup>	Issue Date	Name of Patentee or Applicant of cited Document	Pages,Columns,Lines where Relevant Passages or Relevant Figures Appear
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Examiner Initial*	Cite No	Publication Number	Kind Code <sup>1</sup>	Publication Date	Name of Patentee or Applicant of cited Document	Pages,Columns,Lines where Relevant Passages or Relevant Figures Appear
	1	20040256217	A1	2004-12-23	Applied Materials, Inc.	
	2	20060070875	A1	2006-04-06	Applied Materials, Inc.	
	3	20010007302	A1	2001-07-12	Liubo Hong	
	4	20080318433	A1	2008-12-25	Lam Research Corporation	
	5	20080038481	A1	2008-02-14	Applied Materials, Inc.	

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6	20050048876	A1	2005-03-03	Applied Materials, Inc.	
7	20070059460	A1	2007-03-15	Applied Materials, Inc.	
8	20070283884	A1	2007-12-13	Applied Materials, Inc.	
9	20070173059	A1	2007-07-26	Applied Materials, Inc.	
10	20070170052	A1	2007-07-26	Applied Materials, Inc.	
11	20070125646	A1	2007-06-07	Applied Materials, Inc.	
12	20080196661	A1	2008-08-21	Brian West	
13	20080156264	A1	2008-07-03	Novellus Systems, Inc.	
14	20080164146	A1	2008-07-10	Tosoh SMD, Inc.	
15	20060278341	A1	2006-12-14	Samsung Electronics Co., Ltd.	
16	20030000648	A1	2003-01-02	Samsung Electronics Co., Ltd.	

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17	20070051472	A1	2007-03-08	Tokyo Electron Limited	
18	20070215279	A1	2007-09-20	Tokyo Electron Limited	
19	20070169891	A1	2007-07-26	Tokyo Electron Limited	
20	20080000876	A1	2008-01-03	Hynix Semiconductor Inc.	
21	20080066868	A1	2008-03-20	Tokyo Electron Limited	
22	20080087382	A1	2008-04-17	Tokyo Electron Limited	
23	20080149595	A1	2008-06-26	Peter Cirigliano	
24	20060172542	A1	2006-08-03	Applied Materials, Inc.	
25	20060193102	A1	2006-08-31	Kallol Bera, et al.	
26	20070023145	A1	2007-02-01	Kallol Bera, et al.	
27	20080110760	A1	2008-05-15	Applied Materials, Inc.	

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28	20080223725	A1	2008-09-18	Applied Materials, Inc.	
29	20080017516	A1	2008-01-24	Applied Materials, Inc.	
30	20090041951	A1	2009-02-12	Lam Research Corporation	
31	20080041820	A1	2008-02-21	Lam Research Corporation	
32	20080156264	A1	2008-07-03	Novellus Systems, Inc.	
33	20070062452	A1	2007-03-22	Applied Materials, Inc.	
34	20040118521	A1	2004-06-24	Applied Materials, Inc.	
35	20070102286	A1	2007-05-10	Applied Materials, Inc.	
36	20070051472	A1	2007-03-08	Tokyo Electron Limited	
37	20080066868	A1	2008-03-20	Tokyo Electron Limited	
38	20070215279	A1	2007-09-20	Tokyo Electron Limited	

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39	20070224709	A1	2007-09-27	Tokyo Electron Limited	
40	20080178801	A1	2008-07-31	Applied Materials, Inc.	
41	20060254717	A1	2006-11-16	Hiroyuki Kobayashi, et al.	
42	20070151947	A1	2007-07-05	Teong Su Song, et al.	
43	20080280066	A1	2008-11-13	Corus Technology BV	
44	20070034154	A1	2007-02-15	Tokyo Electron Limited	
45	20070181064	A1	2007-08-09	Tokyo Electron Limited	
46	20080110747	A1	2008-05-15	Applied Materials, Inc.	
47	20050006222	A1	2005-01-13	Peijun Ding, et al.	
48	20050255691	A1	2005-11-17	Applied Materials, Inc.	
49	20050199491	A1	2005-09-15	Applied Materials, Inc.	

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50	20070134907	A1	2007-06-14	Tokyo Electron Limited	
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**FOREIGN PATENT DOCUMENTS**

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